

BF8629 Series

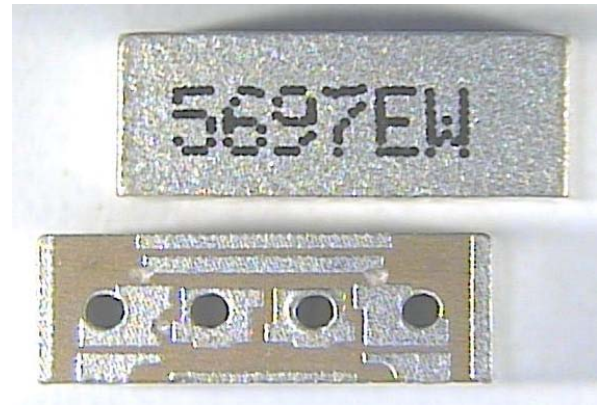
Band-pass filters

Features

- ❖ SMD type with low loss at pass-band and high attenuation at stop-band.
- ❖ RoHS compliant

Applications

- ❖ Wireless communication systems.



Specifications

Part Number	Frequency Range (MHz)	Insertion Loss @ BW (dB)	Ripple @ BW (dB)	Return Loss @ BW (dB)	Frequency (MHz)	Attenuation (dB)
BF8629-5R7-360	5490 ~ 5850	2.5 max.	1.3 max.	10 min.	5150 ~ 5330	50 min.

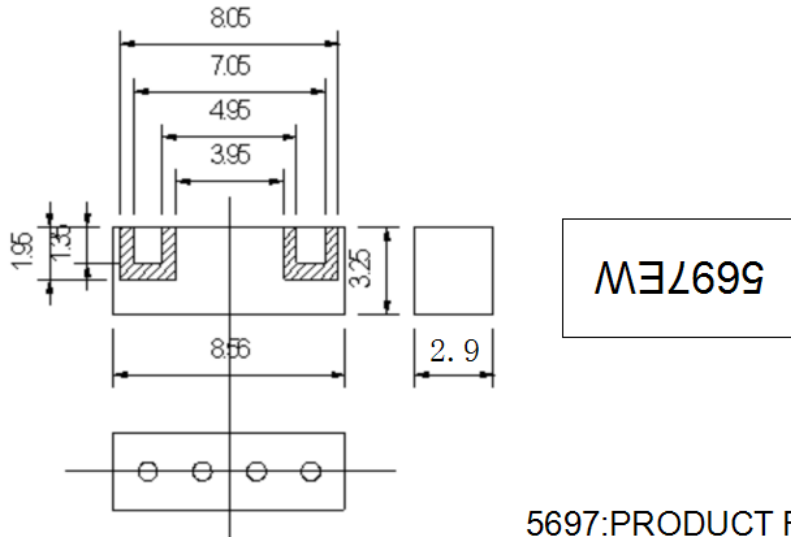
Q'ty/Reel (pcs) : 1,000
 Operating Temperature Range : -40 ~ +100 °C
 Storage Temperature Range : -40 ~ +100 °C
 Storage Period : 12 months max.
 Power Capacity : 1W max.

Part Number

BF **8629** - **5R7** - **360** **□** **/LF**
 ① ② ③ ④ ⑤ ⑥

① Type	BF : Band-Pass Filter	② Dimensions (L x W)	8.6 x 2.9 mm
③ Frequency Range	5R7=5700MHz	④ Specification Code	360
⑤ Packaging	T: Tape & Reel B: Bulk	⑥ Soldering	/LF=lead-free

Terminal Configuration



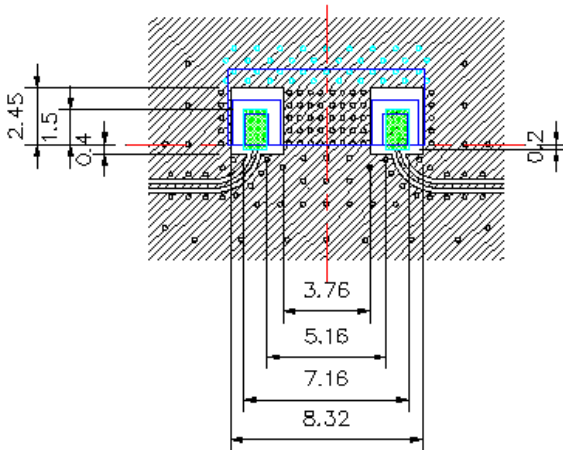
Dimensions in mm
Tolerance: ± 0.25

5697:PRODUCT FREQUENCY(5697MHz)
E : PRODUCT CODE(ACX)
W : DATE CODE

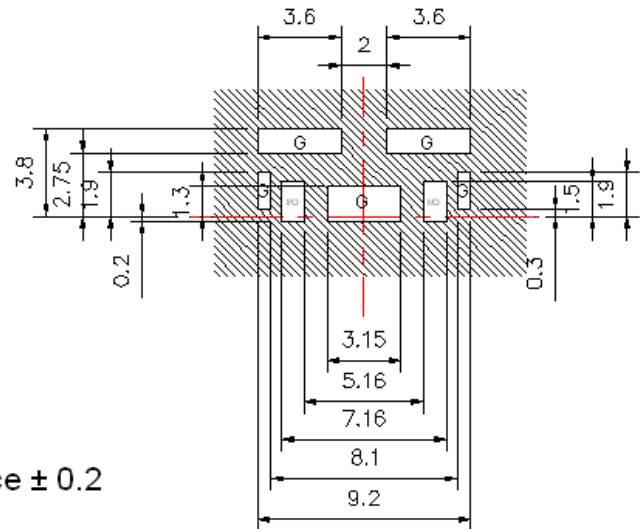
Dimensions and Recommended PC Board Pattern

Unit: mm

Conductive Material Pattern



Solder resist pattern



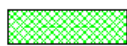
Tolerance ± 0.2



Electrode



Solder Resist

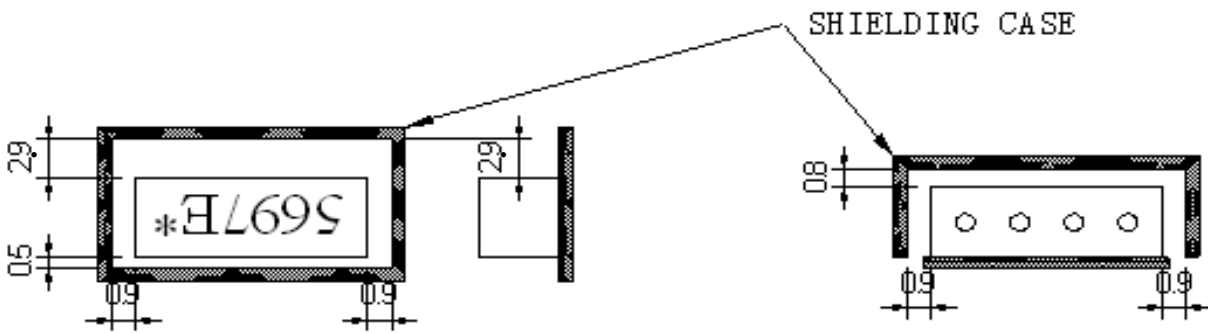


I/O Pads must be connected to line with 50 ohm impedance.
In the application a termination of 50 ohm be realized.

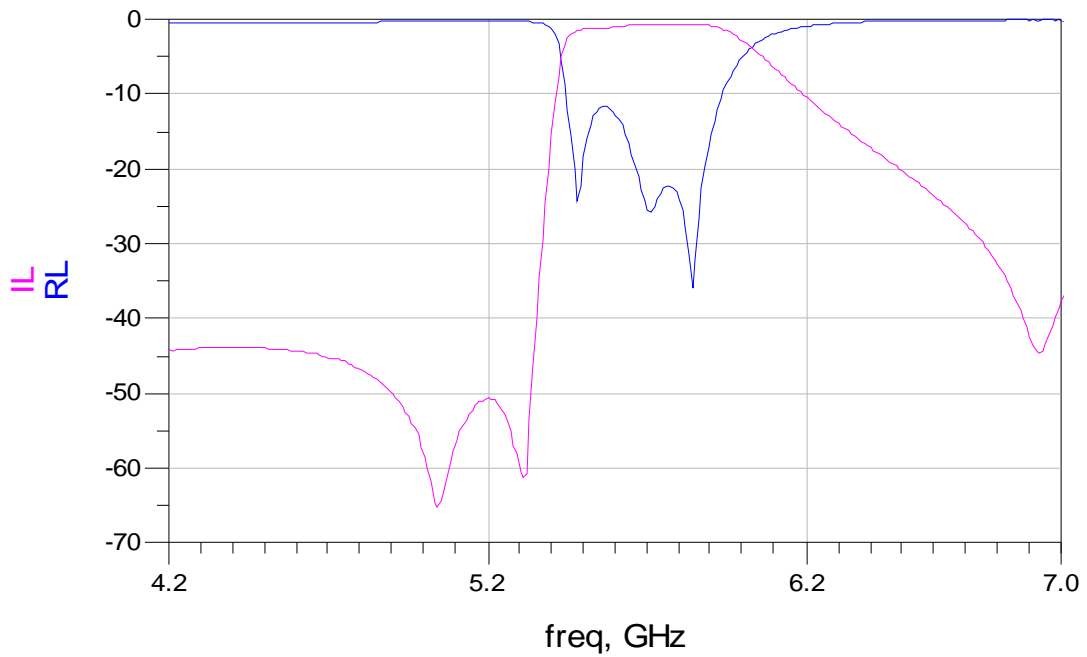


Solder LAND

Shielding case layout guide (min)



Electrical Characteristics (T=25oC)

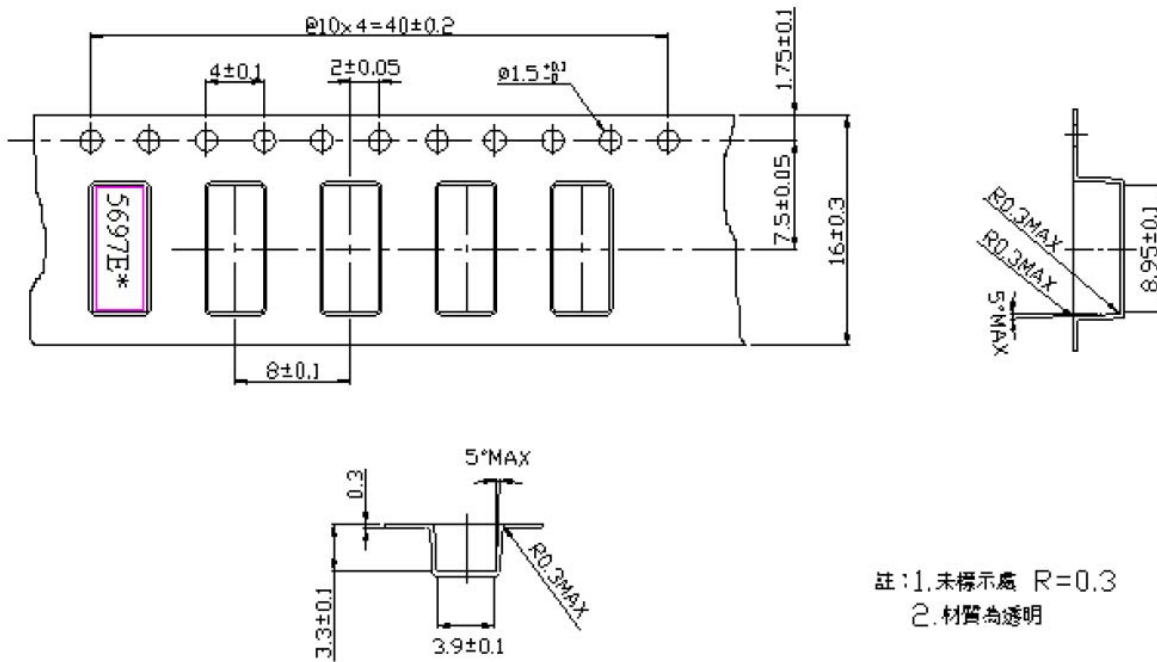


Notes

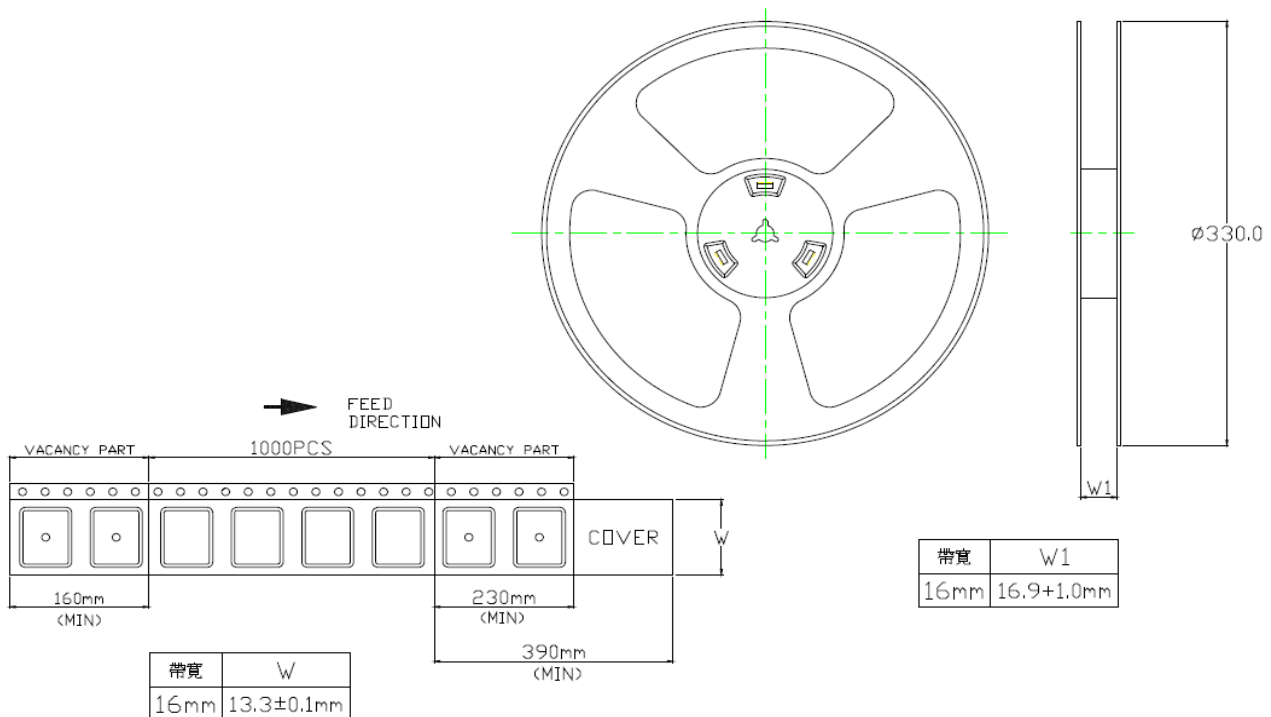
- ❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

Taping Specifications

❖ Tape Dimensions (Unit: mm) & Quantity



❖ Reel Dimensions (Unit: mm)



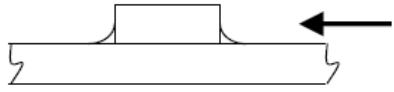
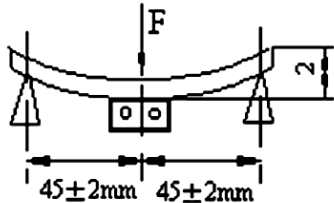
❖ Storage Conditions

(1) Temperature: $0 \sim 40^\circ\text{C}$, humidity : 80%RH or less

(2) Storage Period: 12 months max.*

*12 months in vacuum sealed bag and 1 month after opened. Please keep unused parts in vacuum sealed bags.

Mechanical & Environmental Characteristics

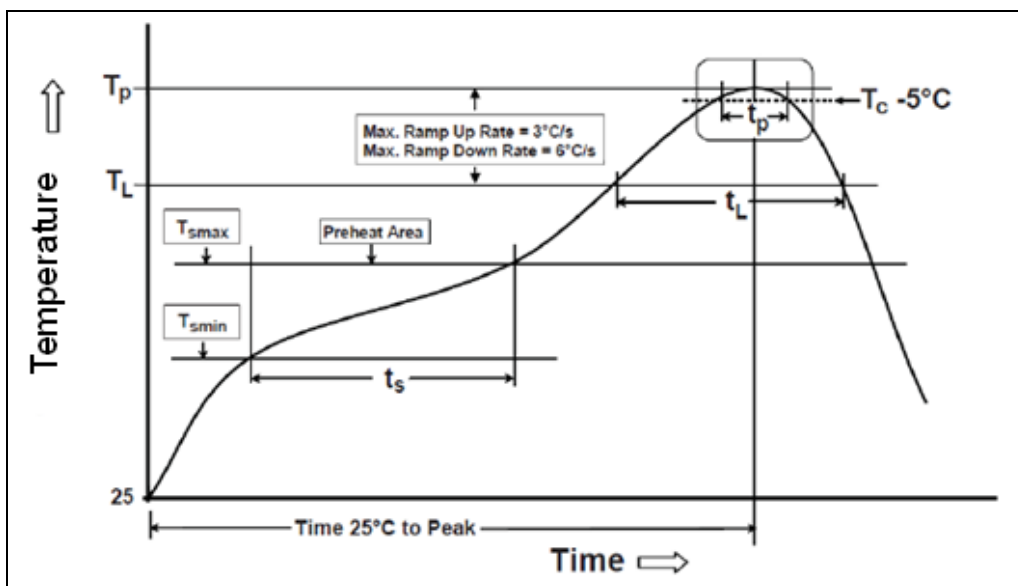
Item	Requirements	Test Method
Low Temperature Hold Test	1. No apparent damage 2. Fulfill the electrical specification after test	Unit shall be subjected to -40°C for 10 hours and then be left for more than 2 hours at room temperature.
High Temperature Hold Test	1. No apparent damage 2. Fulfill the electrical specification after test	Unit shall be subjected to $+100^{\circ}\text{C}$ for 10 hours and then be left for more than 2 hours at room temperature.
Humidity Resistance Test	1. No apparent damage 2. Fulfill the electrical specification after test	Unit shall be subjected to the $60\pm 2^{\circ}\text{C}$, 95% relative humidity for 24 hours and then be left for more than 2 hours at $25\pm 5^{\circ}\text{C}$ in less than 65% relative humidity.
Thermal Shock Resistance Test	1. No apparent damage 2. Fulfill the electrical specification after test	After the unit is applied to thermal shock $-40^{\circ}\text{C} \leftrightarrow +100^{\circ}\text{C}$ for 2 hours soak at each temperature with transition time less than 10 seconds for 5 cycles and then be left for more than 1 hour at $25\pm 5^{\circ}\text{C}$ in less than 65% relative humidity.
Adhesion Test	1. No apparent damage	The device is subjected to be soldered on test PCB. Then apply 0.5Kg(5N) of force for 10 ± 1 seconds in the direction of arrow. (the soldering should be done by reflow and be conducted with care so that the soldering is uniform and free of defect by stress such as heat shock.) 
Bending Resist Test	1. No apparent damage	Weld the product to the center part of the PCB with the thickness $1.6\pm 0.2\text{mm}$ as the illustration shows, and keep exerting force arrow-ward on it as speed off 1mm/S , and hold for $5\pm 1\text{S}$ at the position of 1.5mm . 

Soldering Conditions

❖ Recommended Reflow Soldering Profile for Pb-free Process

Phase	Profile features	Pb-Free Assembly (SnAgCu)
Preheat	-Temperature min(T_{smin})	150°C
	-Temperature max(T_{smax})	200°C
	-Time(t_s) from (T_{smin} to T_{smax})	60-120 seconds
Ramp-up	Avg. Ramp-up rate(T_{smax} to T_P)	3°C/second(max)
Reflow	-Temperature(T_L)	217°C
	-Total time above T_L (t_L)	30-100 seconds
Peak	-Temperature(T_P)	260°C
	-Time(t_p)	3 second
Ramp-down	Rate	6°C/second max.
Time from 25°C to peak temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu

Note: All the temperature measure point is on top surface of the component. If temperature over recommend, it will make component surface peeling or damage.



❖ Soldering With Iron

Soldering iron temperature: $270 \pm 10^\circ\text{C}$

Apply preheating at 120°C for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron over temperature $270 \pm 10^\circ\text{C}$ or Soldering iron can not leakage of electricity.

Notes

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